

S/N Unknown

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

|             |   |                 |            |
|-------------|---|-----------------|------------|
| Applicant:  | Kie Y. Ahn et al.   | Examiner:       | Unknown    |
| Serial No.: | Unknown   | Group Art Unit: | Unknown    |
| Filed:      | Herewith  | Docket:         | 303.686US3 |
| Title:      | MULTILEVEL COPPER INTERCONNECTS WITH LOW-K DIELECTRICS AND AIR GAPS |                 |            |

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INFORMATION DISCLOSURE STATEMENT

MS Patent Application  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement.

Pursuant to 37 C.F.R. §1.98(d), copies of the listed documents are not provided as these references were previously cited by or submitted to the U.S. Patent Office in connection with Applicants' prior U.S. application, Serial No. 10/093244, filed on March 06, 2002, which is relied upon for an earlier filing date under 35 U.S.C. §120.

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

KIE Y. AHN ET AL.

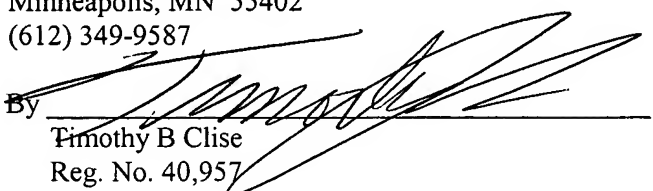
By their Representatives,

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P.O. Box 2938  
Minneapolis, MN 55402  
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Date

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|  |                                |                    |
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| Substitute for form 1449A/PTO<br><b>INFORMATION DISCLOSURE<br/>STATEMENT BY APPLICANT</b><br>(Use as many sheets as necessary) | <i>Complete if Known</i>       |                    |
|  | <b>Application Number</b>      | Unknown            |
|  | <b>Filing Date</b>             | Even Date Herewith |
|  | <b>First Named Inventor</b>    | Ahn, Kie           |
|  | <b>Group Art Unit</b>          | Unknown            |
|  | <b>Examiner Name</b>           | Unknown            |
| Sheet 1 of 13  | Attorney Docket No: 303.686US3 |                    |

| US PATENT DOCUMENTS |                     |                  |   |       |          |                            |
|---------------------|---------------------|------------------|---|-------|----------|----------------------------|
| Examiner Initial *  | USP Document Number | Publication Date | Name of Patentee or Applicant of cited Document | Class | Subclass | Filing Date If Appropriate |
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**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

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|                             |                    |
|-----------------------------|--------------------|
| <b>Application Number</b>   | Unknown            |
| <b>Filing Date</b>          | Even Date Herewith |
| <b>First Named Inventor</b> | Ahn, Kie           |
| <b>Group Art Unit</b>       | Unknown            |
| <b>Examiner Name</b>        | Unknown            |

Sheet 2 of 13

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|  | Application Number             | Unknown            |
|  | Filing Date                    | Even Date Herewith |
|  | First Named Inventor           | Ahn, Kie           |
|  | Group Art Unit                 | Unknown            |
|  | Examiner Name                  | Unknown            |
| Sheet 3 of 13  | Attorney Docket No: 303.686US3 |                    |

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|  | <b>Filing Date</b>             | Even Date Herewith |
|  | <b>First Named Inventor</b>    | Ahn, Kie           |
|  | <b>Group Art Unit</b>          | Unknown            |
|  | <b>Examiner Name</b>           | Unknown            |
| Sheet 4 of 13  | Attorney Docket No: 303.686US3 |                    |

|  |              |            |                                     |     |        |            |
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| <b>Group Art Unit</b>       | Unknown            |
| <b>Examiner Name</b>        | Unknown            |

Sheet 5 of 13

Attorney Docket No: 303.686US3

|  |              |            |                              |     |        |            |
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Substitute Disclosure Statement Form (PTO-1449)

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. 1 Applicant's unique citation designation number (optional) 2 Applicant is to place a check mark here if English language Translation is attached

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**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**  
(Use as many sheets as necessary)

Complete if Known

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|-----------------------------|--------------------|
| <b>Application Number</b>   | Unknown            |
| <b>Filing Date</b>          | Even Date Herewith |
| <b>First Named Inventor</b> | Ahn, Kie           |
| <b>Group Art Unit</b>       | Unknown            |
| <b>Examiner Name</b>        | Unknown            |

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Attorney Docket No: 303.686US3

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| Substitute for form 1449A/PTO<br><b>INFORMATION DISCLOSURE<br/>STATEMENT BY APPLICANT</b><br><i>(Use as many sheets as necessary)</i> | <div style="border: 1px solid black; padding: 2px;"> <i>Complete if Known</i> </div> <table border="1" style="width: 100%; border-collapse: collapse;"> <tr> <td style="width: 50%;"><b>Application Number</b></td> <td>Unknown</td> </tr> <tr> <td><b>Filing Date</b></td> <td>Even Date Herewith</td> </tr> <tr> <td><b>First Named Inventor</b></td> <td>Ahn, Kie</td> </tr> <tr> <td><b>Group Art Unit</b></td> <td>Unknown</td> </tr> <tr> <td><b>Examiner Name</b></td> <td>Unknown</td> </tr> </table> | <b>Application Number</b> | Unknown | <b>Filing Date</b> | Even Date Herewith | <b>First Named Inventor</b> | Ahn, Kie | <b>Group Art Unit</b> | Unknown | <b>Examiner Name</b> | Unknown |
| <b>Application Number</b>   | Unknown   |                           |         |                    |                    |                             |          |                       |         |                      |         |
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| <b>Examiner Name</b>  | Unknown   |                           |         |                    |                    |                             |          |                       |         |                      |         |
| Sheet 7 of 13   | Attorney Docket No: 303.686US3  |                           |         |                    |                    |                             |          |                       |         |                      |         |

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| Examiner<br>Initials*    | Foreign Document No | Publication Date | Name of Patentee or Applicant of<br>cited Document | Class | Subclass | T <sup>2</sup> |
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| Examiner<br>Initials*                              | Cite<br>No <sup>1</sup> | Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item<br>(book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s),<br>publisher, city and/or country where published.                | T <sup>2</sup> |  |
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|   | <b>First Named Inventor</b>    | Ahn, Kie           |
|   | <b>Group Art Unit</b>          | Unknown            |
|   | <b>Examiner Name</b>           | Unknown            |
| Sheet 8 of 13   | Attorney Docket No: 303.686US3 |                    |

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**DATE CONSIDERED**

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|---|---|--------------------------|--|---------------------------|---------|--------------------|--------------------|-----------------------------|----------|-----------------------|---------|----------------------|---------|
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| <b>First Named Inventor</b>   | Ahn, Kie  |                          |  |                           |         |                    |                    |                             |          |                       |         |                      |         |
| <b>Group Art Unit</b>   | Unknown   |                          |  |                           |         |                    |                    |                             |          |                       |         |                      |         |
| <b>Examiner Name</b>  | Unknown   |                          |  |                           |         |                    |                    |                             |          |                       |         |                      |         |
| Sheet 9 of 13   | Attorney Docket No: 303.686US3  |                          |  |                           |         |                    |                    |                             |          |                       |         |                      |         |

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| <b>Examiner Name</b>  | Unknown   |                          |  |                           |         |                    |                    |                             |          |                       |         |                      |         |
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